

AGENDA
P-2.5 COMMITTEE FOR TANTALUM, NIOBIUM, ALUMINUM CHIP
CAPACITORS
WEDNESDAY, Oct 7, 2009
Savannah, GA.

I. COMMITTEE ORGANIZATION AND PROCEDURE

- 1. Membership and attendance –**
- 2. Approval of agenda –**
- 3. Approval of minutes –**
- 4. Correspondence -**

II. OLD BUSINESS

- 1. Reports**
 - a. S-1 Passive Component Steering Committee –**
 - b. Government Specifications and standards (DSCC representative) –**
 - c. AEC Q200 Subcommittee –**
- 2. Review of Current Active Specifications**
 - a. 535BAAC molded Chip Specification**
 - b. EIA – 809 Applications Guide**
 - c. EIA/IS- 717 Qualification Spec**
 - d. EIA-757 Visual and Mechanical Guide**
 - e. EIA-953 Polymer Tantalum Specifications**
- 3. Review of Current PNs to stay Active**
 - a. PN 5138 – MicroMini Design**
 - b. PN 5137 – Facedown Design**
 - c. PN 5100 – EIA-757 Revision**
 - d. PN 5098 – EIA-809 Revision**
 - e. PN 5097 – IS-717A Update**
- 4. Review of Current Component Bulletins**
 - a. Shelf life of tantalums –**
 - b. Correct Orientation of Tantalum and MLC Capacitors in EIA-481**

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5. Recommendation to Archive Specs:

- a. 535BAAE – Molded Ta Chips Low ESR**
- b. 535BAAD – Molded Ta Chips Protected, Extended Range**

III. NEW BUSINESS

1. List of proposed specification actions

- a. Need to include “scope” for specs on ECA web.**
- b. Need to revise spec info on web**
- c. Specs we need to revise**
- d. other specs we need to have**

2. Component Bulletins

- a. New CB’s needed? –**

3. Other New Business -

IV. ADJOURNMENT –